**MIXED TECHNOLOGY HEADER**

**SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com/MIT

Insulator Material: Liquid Crystal Polymer  
Contact Material: Phosphor Bronze  
Plating: Au or Sn over 50 µ" (1.27 µm) Ni  
Operating Temp Range: -55 °C to +125 °C  
Voltage Rating: 275 VAC  
Max Cycles: 100  
RoHS Compliant: Yes

**PROCESSING**

Lead-Free Solderable: Yes  
SMT Lead Coplanarity: (0.10 mm) .004" max (019-057)  
Board Stacking: For applications requiring more than two connectors per board contact pg@samtec.com

**RECOGNITIONS**

For complete scope of recognitions see www.samtec.com/quality

**ALSO AVAILABLE**

- 11 mm, 16 mm, 18.75 mm and 22 mm stack height  
- 30 µ" (0.76 µm) Gold  
- Differential Pair and “Partitionable” (combine differential & single-ended banks in same connector) available.  
- 76, 95, 114 and 133 positions per row

**Board Mates:** MIS  
**Standoffs:** SO

**HIGH-SPEED CHANNEL PERFORMANCE**

**MIT/MIS @ 5 mm Mated Stack Height**

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

**MIT – NO. OF POSITIONS PER ROW – LEAD STYLE – PLATING OPTION – D – OTHER OPTION**

- **019, 038, 057** (38 total positions per bank)  
- **Specify LEAD STYLE from chart**

**MIT LEAD STYLE**

- **–01**  
- **–02**

**PLATING OPTION**

- **–F** = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails
- **–L** = 10 µ" (0.25 µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails
- **–C** = Electro-Polished Selective 50 µ" (1.27 µm) min Au over 150 µ" (3.81 µm) Ni on Signal Pins in contact area, 10 µ" (0.25 µm) min Au over 50 µ" (1.27 µm) Ni on Ground Plane in contact area, Matte Tin over 50 µ" (1.27 µm) min Ni on all solder tails  

**MATED HEIGHT**

- **–01** (5.00) .197  
- **–02** (8.00) .315

*Note: –C Plating passes 10 year MFG testing

**Note:** Rugged through-hole ground plane soldered to board (requires paste-over-hole, not press-fit) for added retention to PCB.

Due to technical progress, all designs, specifications and components are subject to change without notice.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.

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